Welcome to O-leading

We are professional PCB manufacturer with more than ten years experiences . Products range-single, double side ,multi-layer PCB ,flexible PCB and MCPCB.We can provide fast prototype service – S/S in 24hrs , 4-8layers in 48-96 working hrs production time.

COPPER PLATE HOLES MINIMUM .025 AVG, .020 MIN.. HOLES MAY NOT BE PLUGGED

Pack with colorless transparent bubble film ,25 PCS/ bag, put desiccant in flank, put humidity indicator card on top side

Product Description

led pcb board Printed circuit board
Printed circuit board in china
pcb manufacturer in china

Quick Details

Place of Origin	Guang dong, China (Mainland)	Brand Name	O-Leading
Base Material	FR-4,,Aluminum	Copper Thickness	0.5oz-5oz
Min. Hole Size	0.2mm	Min. Line Width	0.2mm
Surface Finishing	immersion gold ,OSP,lead free HASL	Board Thickness	0.1-5mm
applicable to	led,mobile phone,air conditioners,washing machines	character	Industrial Control pcb
certificates	ISO9001,UL,RoHS,SGS	Q/CTN	10PCS-100PCS
weight	0.01kg -5kg	MOQ	10pcs
color	blue ,red ,green,black.yellow	Min. Line Spacing	0.2mm
Model Number	power bank pcb assembly pcba manufacturer	price	$0.1-$10
desigh type	client requirement	size	0.01m3-10m3

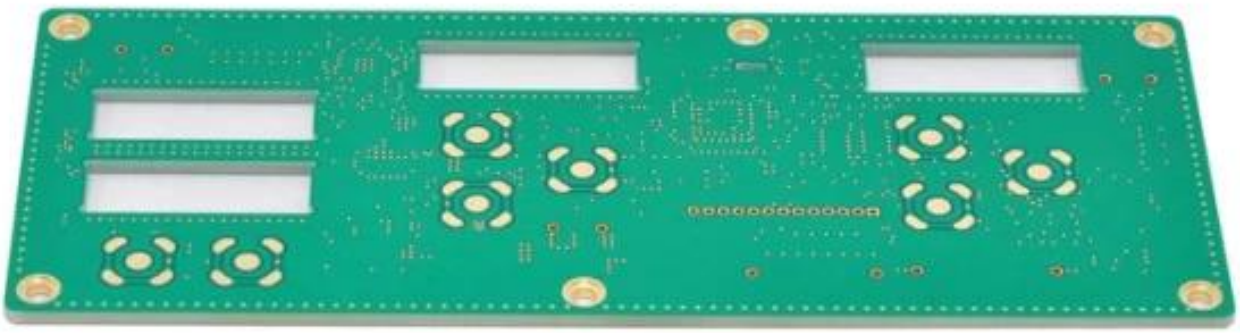
Packaging & Delivery

Packaging Details:	16 years professional OEM pcb board manufacturer
Delivery Detail:	7-12days

Product Description

item	2014		2015~2016		2017~2018	
	Volume	Sample	Volume	Sample	Volume	Sample
Layer count	32	42	38	44	42	48
Min Line/space (μm)	50/50	40/45	40/45	40/40	35/40	35/35
Min drill hole diameter (mm)	0.15	0.10	0.15	0.10	0.15	0.10
Aspect ratio of PTH	14:1	16:1	16:1	18:1	18:1	20:1
N+C+N	4+C+4	5+C+5	5+C+5	6+C+6	5+C+5	6+C+6
Any layer interconnection	5+2+5	6+2+6	5+2+5	6+2+6	5+2+5	6+2+6
Plate filling via	YES	--	YES	--	YES	--
Min. core thickness (exclude copper) (μm)	50	40	40	30	40	30
Min. Laser Drill diameter (μm)	75	65	65	50	50	40
Via on buried hole/stacked via	YES	--	YES	--	YES	--
Material	FR4, Megtron, Nelco, Rogers, Heavy Copper, etc.					
Embedded capacitor PCB	YES	--	YES	--	YES	--
Surface Process	Lead-free HASL, ENIG, OSP, Immersion silver, Immersion tin, Flash gold, Gold finger plating, Selective hard gold plating, Peelable solder mask, Carbon ink					

O-LEADING
To Be Reliable, To Be Valuable



www.o-leading.com

Our Team

O-LEADING
To Be Reliable, To Be Valuable

Certifications

Quality Management System Certificate

This is to certify that
(Organization Code Certificate : 61691591-000-07-16-8)

O-LEADING SUPPLY CHAIN (HK) CO.,LIMITED

ROOM 603D, 6/F HANG PONT COMMERCIAL BUILDING, 31 TONKIN ST., CHEUNG SHA WAN, KL, HK

has been established the quality management system meeting the requirements of standard

GB/T19001-2008/ISO9001:2008

Scope:

Certification Address: Room 1313, Fortune Building, Nanheng West Road, Huiyang District, Huizhou, Guangdong, China

Certification Activities: Sales and services of printed circuit boards

Certificate No.: 51816Q01163R0S

Issued Date : 2016-11-17 **Valid to :** 2018-09-15

Initial Issued Date : 2016-11-17 **Renewal Date :** ***

GM

CICC INSPECTION CERTIFICATION

CIGG CERTIFICATION
嘉泰认证

QUALITY MANAGEMENT SYSTEM CERTIFICATE

Certificate No: 18118Q10347R0S

We hereby certify that

O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED

Credit No: 61691591-000-07-17-2

Registration Add:ROOM 603D,6/F HANG PONT COMMERCIAL BUILDING,31 TONKIN ST,CHEUNG SHA WAN,KL,HK

Business Add:1313,Floor 13,Fortune Building,Danshui Town,Huiyang District, Huizhou,Guangdong,China

Has implemented and maintains a **Quality Management System**

Which fulfils the requirements of the following standards

GB/T19001-2016 idt ISO9001:2015

Scope of certification

Sales of printed circuit boards

Initial Issuance period: February 27, 2018

This certificate is valid during: February 27, 2018 — February 26, 2021

This certificate is invalid without CICC qualified label in the following period

First supervision and audit	Qualified mark	Second supervision and audit	Qualified mark

CICC IAF CNAS

2017/2/6 ZPMV2.E490354 - Wiring, Printed - Component

UL ONLINE CERTIFICATIONS DIRECTORY

ZPMV2.E490354
Wiring, Printed - Component

For enhanced search functionality, please visit UL's iQ™ Family of Databases.
Click on a product designation for complete information.

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Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN CO LIMITED E490354
Fortune Building, Nanheng West Road
Room 1313
Huizhou, Guangdong 516211, CHINA

	Cond Width				Max			Max			
		Min	Cond	SS/	Area	Solder		Oper		Meets	C
	Min	Edge	Thk	DS/	Diam	Limits		Temp	Flame	UL796	T
Type	mm(in)	mm(in)	mic(mil)	DSO	mm(in)	C	sec	C	Class	DSR	I
Multilayer (mass laminate) printed wiring boards.											
O-LEADING-401											
	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
O-LEADING-407											
	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer printed wiring boards.											
O-LEADING-408											
	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:135	DS	50.8 (2.0)	260	20	130	V-0	All	*
Single layer printed wiring boards.											
O-LEADING-002											
	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING-003											
	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
O-LEADING-033											
	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
O-LEADING-205											
	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-206											
	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.
Last Updated on 2017-01-27

Questions? Print this page Terms of Use Page Top

http://database.ul.com/cgi-bin/XYV/cgifind.exe/SEC?TRANSLATE+ON+/tmp/cgi-bin/temp-ZPMV2.E490354.xml+Wiring,+Printed+-+Component&top=1 1/2

SGS

Test Report No. CANEC1805164701 Date: 03 Apr 2018 Page 2 of 6

Test Results :

Test Part Description :

Specimen No.	SGS Sample ID	Description
SN1	CAN18-051647.001	Green "PCB"

Remarks :

(1) 1 mg/kg = 1 ppm = 0.0001%
(2) MDL = Method Detection Limit
(3) ND = Not Detected (< MDL)
(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC62321-5:2013, IEC62321-7-2:2017 , IEC 62321-6:2015 and IEC62321-8:2017, analyzed by ICP-OES , UV-Vis and GC-MS .

Test Item(s)	Limit	Unit	MDL	001
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	9
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (CrVI)	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Monobromobiphenyl	-	mg/kg	5	ND
Dibromobiphenyl	-	mg/kg	5	ND
Tribromobiphenyl	-	mg/kg	5	ND
Tetrabromobiphenyl	-	mg/kg	5	ND
Pentabromobiphenyl	-	mg/kg	5	ND
Hexabromobiphenyl	-	mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl	-	mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Monobromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Tribromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND

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Attention: To check the authenticity of testing / inspection report & certificate, please contact us at telephone: (86-755) 8307 1443, or email: CN.Doccheck@sgs.com

Packaging & Delivery

Packaging Details	16 years professional OEM pcb board manufacturer
Delivery Detail	7-12days

FAQ

1. How do O-Leading ensure quality?
Our high quality standard is achieved with the following.
1.The process is strictly controlled under ISO 9001:2008 standards.
2.Extensive use of software in managing the production process
3.State-of-art testing equipments and tools. E.g. Flying Probe, X-ray Inspection, AOI (Automated Optical Inspector) and ICT (in-circuit testing).
4.Dedicated quality assurance team with failure case analysis process
5.Continuous staff training and education

2. How do O-Leading keep your price competitive?
Over the last decade, prices of many raw materials (e.g. copper, chemicals) had doubled, tripled or quadrupled; Chinese currency RMB had appreciated 31% over US dollar; And our labor cost also increased significantly. However, O-Leading have kept our pricing steady. This owns entirely to our innovations in reducing cost, avoiding wastes and improving efficiency. Our prices are very competitive in the industry at the same quality level.
We believe in a win-win partnership with our customers. Our partnership will be mutually beneficial if we can provide you an edge on cost and quality.

3. What kinds of boards can O-Leading process?
Common FR4, high-TG and halogen-free boards, Rogers, Arlon, Telfon, aluminum/copper-based boards, PI, etc.

4. What data are needed for PCB production?
It is best to provide data in Gerber 274-X format. In addition, Cam350, CAD, Protel 99se, PADS, DXP and Eagle can also be processed.

5. What's the typical process flow for multi-layer PCB?
Material cutting → Inner dry film → inner etching → Inner AOI → Multi-bond → Layer stack up Pressing → Drilling → PTH → Panel Plating → Outer Dry Film → Pattern Plating → Outer etching → Outer AOI → Solder Mask → Component Mark → Surface finish → Routing → E/T → Visual Inspection.